IPC ASSOCIATION CONNELECTRONICS INDU	Material Comp © Copyright 2005. I international and Pa	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
Supplier Inf	formation													
Company name*				Company unique ID			Unique ID Authority				Response Date*			
nsemi											2023-06-08			
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-S	Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorized Rep	presentative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product				roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Req	quester Item Number	Mfr Item	r Item Number Mfr Item		fr Item Name		Effective Date	e Versio	n I	Manufacturing Site		Weight*	UOM	Unit Type
		NB3L202KMNTXG 1:2 HCSL Fanout Buffer		Buffer		2023-06-08		1	MY1		26.42	mg	Each	
Ianufactur	ring Proccess Informa	ntion							,					
Terminal Plating / Grid Array Material			Ferminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Tem		Temperatu	erature Max Time at Peak Ten		ture Numb	per of Reflow Cyc	eles	
Matte Tin (Sn) - annealed			CU Alloy 1				260 C 30			seconds 3				
omments														
vel 1 - maxim	um time at peak temperati	ure during so	ldering is 10-3	0 seconds										
or more infor	mation regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.28	mg	Supplier	Silicon (Si)	7440-21-3		1.28	mg
Die Attach	0.22	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.044	mg
			Supplier	Silver (Ag)	7440-22-4		0.176	mg
Lead Frame	10.18		Supplier	Silver (Ag)	7440-22-4		0.1527	mg
			Supplier	Tin (Sn)	7440-31-5		0.0255	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0224	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0255	mg
			Supplier	Copper (Cu)	7440-50-8		9.954	mg
Mold Compound-Black	14.24			Epoxy resin	proprietary data		0.6693	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.424	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0142	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.4632	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.6693	mg
Plating	0.36	mg	Supplier	Tin (Sn)	7440-31-5		0.36	mg
Wire Bond - Au	0.14	mg	Supplier	Gold (Au)	7440-57-5		0.14	mg